

# **Express-IBR**

Extreme Rugged COM Express<sup>®</sup> Basic Size Type 6 Module with Intel<sup>®</sup> Core<sup>™</sup> Processor with Intel<sup>®</sup> QM77 Express Chipset

### Features

- Intel<sup>®</sup> qual or dual Core<sup>™</sup> i7/i3 Processor with Mobile Intel<sup>®</sup> QM77 Express Chipset
- Up to 16GB DDR3 with ECC support in two SODIMM sockets at 1600MHz
- Three Digital Display Interfaces (DDI) for HDMI/DVI/DisplayPort or SDVO
- Seven PCIe x1 (Gen 2), one PCIe x16 (Gen 3) for graphics (or general purpose x8/4/1)
- GbE, 2x SATA 6 Gb/s, 2x SATA 3 Gb/s, USB 2.0, 4 USB 3.0
- 50% Thicker PCB for high vibration environments
- Extreme Rugged operating temperature: -40°C to +85°C (build option)



### **Specifications**

### • Core System

### CPU

Intel<sup>®</sup> Core™ i7/i3, 22nm process, BGA type i7-3615QE 2.3GHz, 6MB L3 cache, 45W, quad core i7-3612QE 2.1GHz, 6MB L3 cache, 35W, quad core i7-3555LE 2.5GHz, 4MB L3 cache, 25W, dual core i7-3517UE 1.7GHz, 4MB L3 cache, 17W, dual core i3-3217UE 1.6GHz, 3MB L3 cache, 17W, dual core

Метогу

Dual channel ECC 1600 MHz DDR3 memory up to 16 GB in dual SODIMM sockets

BIOS AMI EFI with CMOS backup in 16 Mb SPI flash

Hardware Monitor Supply voltages and CPU temperature

**Debug Interface** XDP SFF-26 extension for ICE debug

Watchdog Timer Programmable timer range to generate RESET

#### **Expansion Busses**

PCI Express x16 (Gen3) bus for discrete graphics solution or general purpose PCI Express (2 x8 or 1 x8 with 2 x4) 7 PCI Express x1: Lanes 0/1/2/3/4/5/6 LPC bus, SMBus (system), I2C (user)

#### Technologies

PAVP 3.0, Intel® AMT 8.0, Intel® VT, Intel® AES-NI, Intel® HT, Intel® HD Graphics with Dynamic Frequency, Intel® Turbo Boost , Dynamic Turbo, Intel® AVX 1.0, Intel® Quick Sync Video

### Video

Integrated in Processor Intel<sup>®</sup> HD Graphics 4000 at 650-1300 MHz

Integrated Video DirectX 11.0, OpenGL 3.1, and OCL 1.1

Media Processing Decode (HW JPEG & MJPEG decode), encode (full HW MPEG2 encode), transcode Intel® Clear Video HD Technology + enhanced media processing

VGA Interface Analog VGA support with 300 MHz DAC Analog monitor support up to QXGA (2048 x 1536) and VGA hot plug

LVDS Interface Dual channel 18/24-bit LVDS

Digital Display Interface Three DDI ports supporting HDMI/DVI/DisplayPort or SDVO

• Audio

Chipset Integrated in Mobile Intel® QM77 Express chipset

Audio Codec Implemented on carrier board

Ethernet
 Chipset: Intel® Gigabit LAN PHY WG82579LM
 Speed: 10/100/1000 Mbps Ethernet

Note: "build option" indicates an alternative BOM configuration to support additional or alternative functions that are not available on the standard product. Be aware that these "build option" part numbers will need to be newly created and this will result in production lead times.



# **Specifications**

### • I/O Interfaces

Chipset

Integrated in Mobile Intel® QM77 Express chipset

USB

Supports up to eight ports USB 2.0, 4 USB 3.0

### SATA

Two SATA 6 Gb/s, two SATA 3 Gb/s with support for RAID 0,1,5,10

### • Super I/O

Connected to LPC bus on carrier if needed (BIOS supports W83627DHG)

• TPM

Chipset: Atmel AT97SC3204-U1A190 Type: TPM 1.2

### • Power

Input Power: AT mode (12 V +/- 5%) and ATX mode (12 V and 5 Vsb +/- 5%) Power States: Supports S0, S1, S3, S4, S5 Power Consumption: 12W typical (i7-36xxQE) 8W typical (i7-3555LE/i7-3517UE/i3-3217UE) S3: 0.85W S5: 0.55W Smart Battery Support: Yes (BIOS supports LTC4100 and LTC1760)

### Mechanical and Environmental

Form Factor: PICMG COM.0: Rev 2.1 Type 6 Dimension: Basic size: 125 mm x 95 mm Board Thickness: 0.093" (2.3mm)

### **Operating Temperature**

Standard: 0°C to +60°C Extreme Rugged: -40°C to +85°C (build option) Storage Temperature: -55°C to +85°C

### Humidity

90% at +60°C non-condensing

### Shock

50G peak-to-peak, 11ms duration, MIL-STD-202G Method 213B

### Vibration

Operating: 11.96 Grms, 50-20,000 Hz, each axis, MIL-STD-202G Method 214A Certifications: CE, FCC, HALT

### Operating Systems

Standard Support Windows 7, Linux

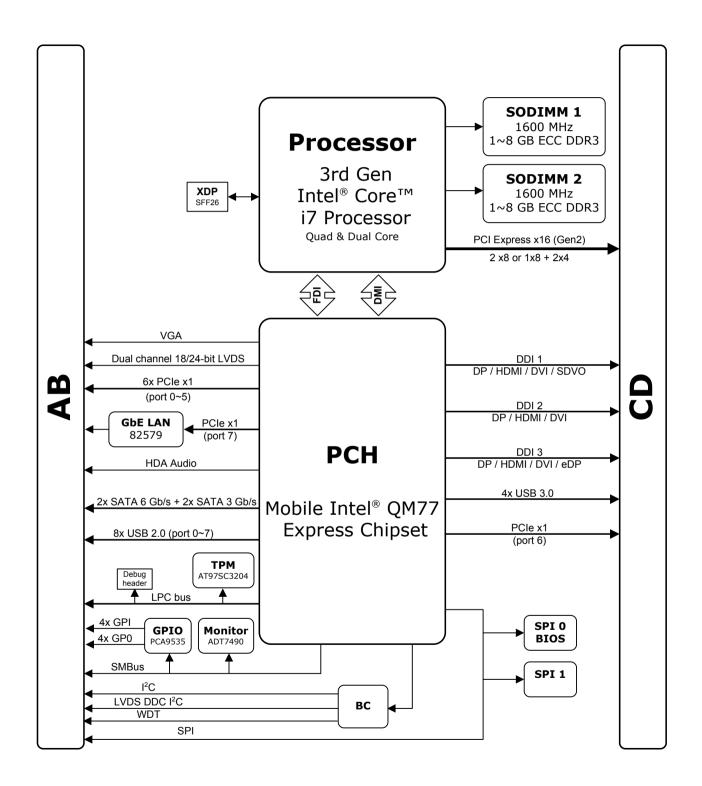
### Extended Support (BSP)

Windows XPe/7, WEC 7, Linux, VxWorks 6.9, QNX 6.5, AIDI Library

Note: "build option" indicates an alternative BOM configuration to support additional or alternative functions that are not available on the standard product. Be aware that these "build option" part numbers will need to be newly created and this will result in production lead times.



### **Functional Diagram**



# Ordering Information

### • Express-IBR-i3-R-3217UE

COM Express<sup>®</sup> Basic Size Type 6 Module with Intel<sup>®</sup> Core™ i3-3217UE 1.6GHz 17W Dual Core CPU, two DDR3 ECC SODIMMs supported

### • Express-IBR-i7-R-3517UE

COM Express<sup>®</sup> Basic Size Type 6 Module with Intel<sup>®</sup> Core<sup>™</sup> i7-3517UE 1.7GHz 17W Dual Core CPU, two DDR3 ECC SODIMMs supported

### • Express-IBR-i7-R-3555LE

COM Express<sup>®</sup> Basic Size Type 6 Module with Intel<sup>®</sup> Core<sup>™</sup> i7-3555LE 2.5GHz 25W Dual Core CPU, two DDR3 ECC SODIMMs supported

### • Express-IBR- i7-R-3612QE

COM Express<sup>®</sup> Basic Size Type 6 Module with Intel<sup>®</sup> Core™ i7-3612QE 2.1GHz 35W Quad Core CPU , two DDR3 ECC SODIMMs supported

### • Express-IBR-i7-R-3615QE

COM Express<sup>®</sup> Basic Size Type 6 Module with Intel<sup>®</sup> Core™ i7-3615QE 2.3GHz 45W Quad Core CPU, two DDR3 ECC SODIMMs supported

### Accessories

### Heat Spreaders

HTS-IBR-B

Heat-spreader for Express-IBR with threaded standoffs for bottom-mounting

### • HTS-IBR-BTF

Heat-spreader for Express-IBR with through-hole standoffs for top-mounting

### Passive Heatsinks

### • THSH-IBR-BTL

Heatsink for Express-IBR with through hole standoffs for top-mounting

### **Active Heatsink**

### THSF-IBR-BTL-CU

Heatsink with FAN for Express-IBR with through-hole standoffs for top-mounting

### Starter Kit

• COM Express Type 6 Starter Kit Plus

COM Express formfactor starter kit with Express-BASE6 board, power supply, and accessory kit



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